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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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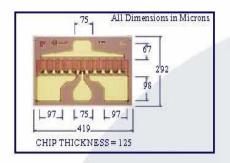


MwT-A9

18 GHz High Gain, Low Noise GaAs FET



DOWNLOAD ADDITIONAL DATA WWW.MWTINC.COM



FEATURES

- IDEAL FOR HIGH DYNAMIC RANGE RECEIVER APPLICATIONS
- 1.6 dB NOISE FIGURE AT 12 GHz
- +24.5 dBm OUTPUT POWER AT 12 GHz
- 9 dB SMALL SIGNAL GAIN AT 12 GHz
- 0.3 MICRON REFRACTORY METAL/GOLD GATE

PARAMETER

- 750 MICRON GATE WIDTH
- AVAILABLE IN CHIP AND PACKAGES

DESCRIPTION

The MwT-A9 is a GaAs MESFET device whose nominal quarter-micron gate length and 750 micron gate width make it ideally suited to applications requiring high-gain in the 500 MHz to 18 GHz frequency range with moderate power output while exhibiting low noise figure. The chip is produced using MwT's reliable metal system and devices from each wafer are screened to insure reliability. All chips are passivated using MwT's patented "Diamond-Like Carbon" process for increased durability, Designers can use MwT's unique BIN selection feature to choose devices from narrow Idss ranges, insuring consistent circuit operation.

DC SPECIFICATIONS AT Ta = 25°C

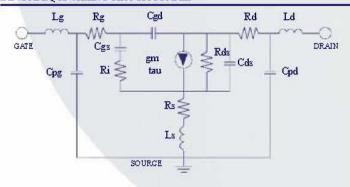
SYMBOL	PARAN	1. & CONDITIONS	UNITS	MIN	TYP	MAX
IDSS	100 PSO 6 LCDV 2 3 20 FG	rain Current VGS= 0.0 V	mA	78		282
Gm	Transcondu Vds= 2.0 V	ctance VGS=0.0 V	mS	95	120	
Vp	Pinch-off V Vds= 3.0 V	oltage IDS= 5.0 mA	v		-2.0	-5.0
BVGSO	Gate-to-Son Igs=-1.0 m	irce Breakdown Volt. A	v	-5.0	-10.0	
BVGDO	Gate-to-Drain Breakdown Volt. Igd= -1.0 m.A.		v	-6 .0	-10.0	
Rth	200700000000000000000000000000000000000	MwT-A9 Chip, A971 MwT-A970, A973 depends on case mount			70 175*	

RF SPECIFICATIONS AT Ta = 25°C

SYMBOL	PARAMETERS AND CONDITIONS	FREQ	UNITS	MIN	TYP
PldB	Output Power at 1 dB Compression VDS=5.0 V Idss=0.6 IDS=120mA	12 GHz	dBm	23.0	24.5
SSG	Small Signal Gain VDS= 5.0 V Idss= 0.6 IDS=120mA	12 GHz	dB	8.5	9.0
NFopt	Optimum Noise Figure VDS= 3.0V IDS= 30mA	12 GHz	dΒ		1.8
GA	Gain at Optimum Noise Figure VDS= 3.0V IDS= 30mA	12 GHz	dB	6.0	6.5

VALUE

DEVICE EQUIVALENT CIRCUIT MODEL



THETHER		7711.		
Source Resistance	Rs	0.80	Ω	
Source Inductance	Ls	0.04	пH	
Drain-Source Resistance	Rd₃	100.0	Ω	
Drain-Source Capacitance	Cds	0.08	pF	
Drain Resistance	Rd	1.0	Ω	
Drain Pad Capacitance	Cpd	0.10	pF	
Drain Inductance	Ld	0.28	nH	
Gate Bond Wire Inductance	Lg	0.10	nH	
Gate Pad Capacitance	Cpg	0.03	pF	
Gate Resistance	Rg	0.50	Ω	
Gate-Source Capacitance	Cgs	0.78	\mathbf{pF}	
Channel Resistance	Ri	0.8	Ω	
Gate-Drain Capacitance	Cgd	0.10	pF	
Transconductance	gm	120.0	mS	
Transit Time	tau	1.0	psec	

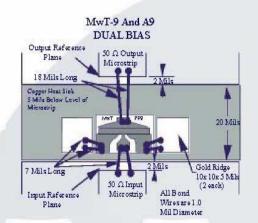
ORDERING INFORMATION

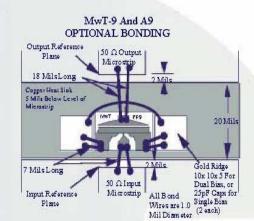
Chip	MwT-A9	NOTE:
Package 70	MwT-A970	For Package information, please see supplimentary application note from our website at
Package 71	MwT-A971	www.mwtinc.com. When placing an order or inquiry, please specify BIN range, wafer no. if
Package 73	MwT-A973	known, and screening level required.

MwT-A9

18 GHz High Gain, Low Noise GaAs FET







325 250 175 100 0 2 406 8 407 150 125 100 75°C or Lower 175 100 0 2 4 6 8 Vds (V)

Absolute Maximum Continuous Maximum

MAXIMUM RATINGS AT Ta = 25°C

PARAMETER	UNITS	CONTMAX	ABSOLUTE MAX
Drain to Source Voltage	v	See Safe Ope	rating Limits
Channel Temperature	•C	+150	+175
Storage Temperature	•C	-65 to +150	+175
RF Input Power	mW	240	360
	Drain to Source Voltage Channel Temperature Storage Temperature	Drain to Source Voltage V Channel Temperature •C Storage Temperature •C	Drain to Source Voltage V See Safe Ope Channel Temperature •C +150 Storage Temperature •C -65 to +150

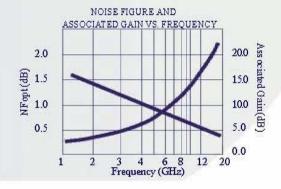
NOTES: 1. Exceeding any one of these limits in continuous operation may reduce the mean-time-to-failure below the design goals.

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2. Exceeding any one of these limits may cause permanent damage.

TYPICAL NOISE PARAMETERS MwT-A9LN Chip: VDS= 3.0V IDS= 35mA

FREQUENCY	NF MIN	GAMI	MA OPT	D (CO
GHz	dB	MAG	ANGLE	Rn/50
1.00	0.30	0.85	4.5	0.19
2.00	0.33	0.69	36.8	0.18
4.00	0.62	0.56	73.4	0.19
6.00	0.93	0.52	106.3	0.19
10.00	1.48	0.57	152.0	0.17
12.00	1.73	0.61	167.3	0.17
16.00	2.19	0.68	-169.8	0.16
18.00	2.40	0.71	-160.8	0.15



Bin Selection Guide

Bin	Α	В	C	D
ldss	78-	114-	150-	222-
Range	114	150	222	258

BIN ACCURACY STATEMENT

When placing order or inquiring, please specify BIN range, wafer no., if known, and screening level required.